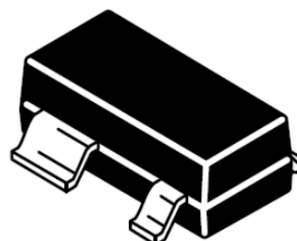


Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 15\text{kV}$
 - Contact discharge: $\pm 8\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 10A (8/20 μs)
- RoHS Compliant

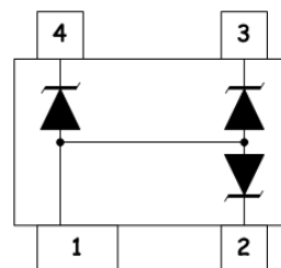
Dimensions SOT-143



Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports
- Peripherals

Pin Configuration



Mechanical Characteristics

- Package: SOT-143
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel: 3,000 pcs
- Reel Size: 7 inch
- Device Marking: 503B

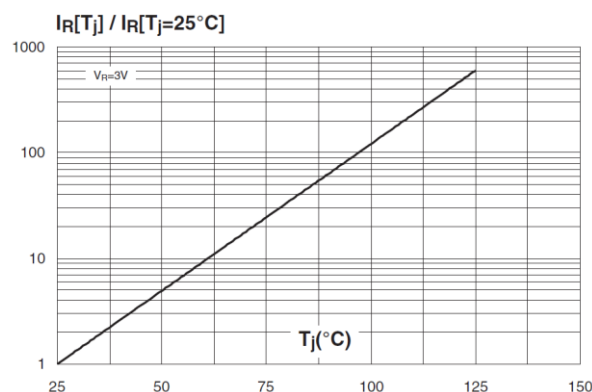
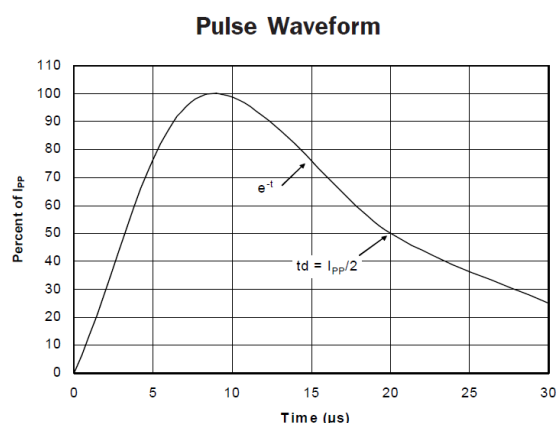
Absolute Maximum Ratings (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P _{pp}	150	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 15	kV
ESD per IEC 61000-4-2 (Contact)		± 8	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STJ}	-55 to +150	°C

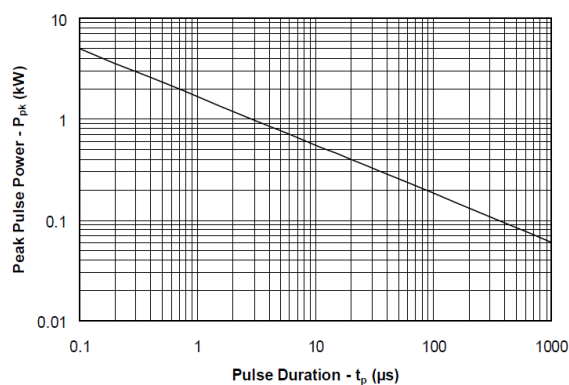
Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				5	V
Breakdown Voltage	V_{BR}	$I_T = 1mA$	6			V
Reverse Leakage Current	I_R	$V_{RWM} = 5V$			1	μA
Clamping Voltage	V_C	$I_{PP} = 1A$ (8 x 20 μs pulse)			10	V
Clamping Voltage	V_C	$I_{PP} = 10A$ (8 x 20 μs pulse)			15	V
Junction Capacitance	C_J	$V_R = 0V, f = 1MHz$		24		pF

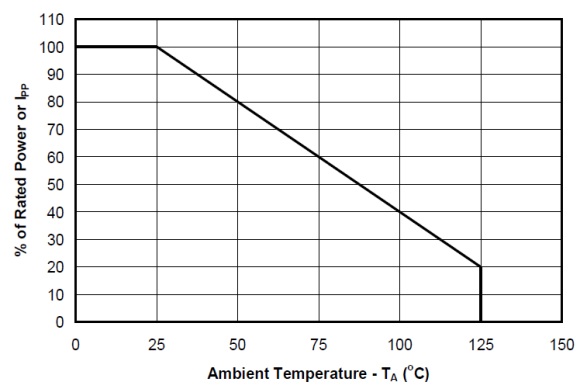
Typical Performance Characteristics (TA=25°C unless otherwise specified)



Non-Repetitive Peak Pulse Power vs. Pulse Time

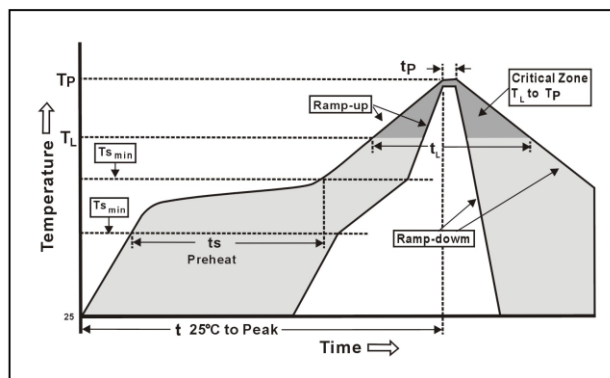


Power Derating Curve

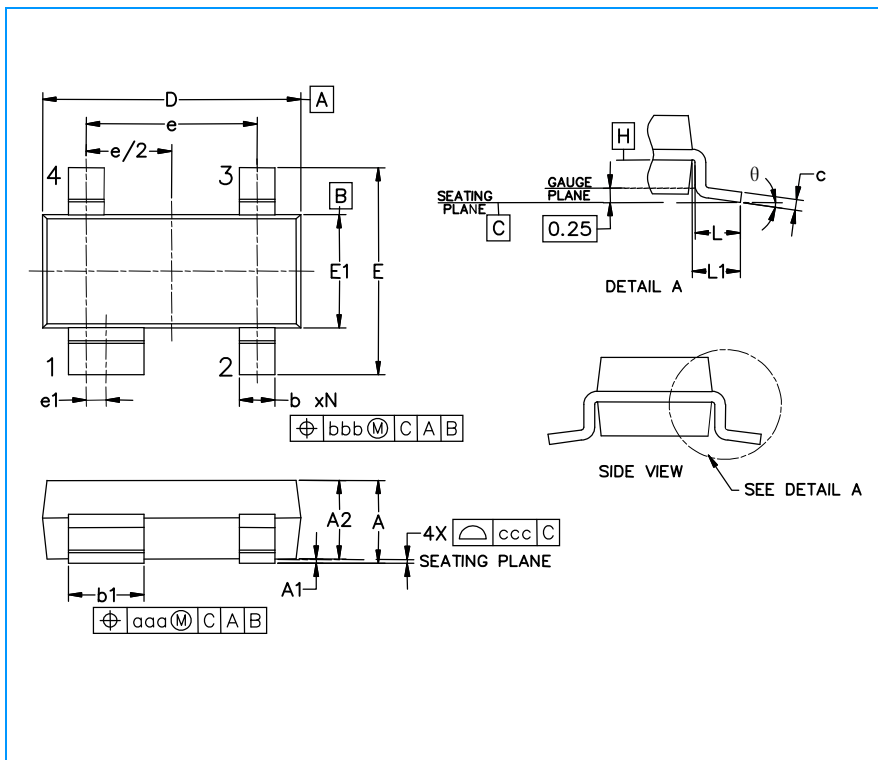


Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(\text{Min})}$)	150°C
	- Temperature Max ($T_{s(\text{Max})}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{s(\text{Max})}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

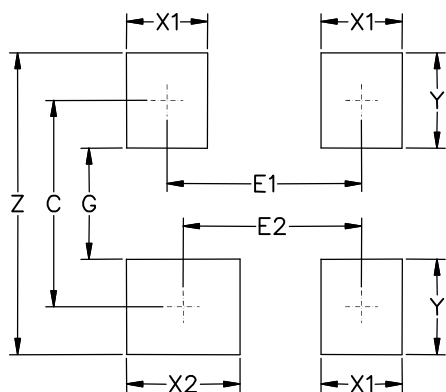


SOT-143 Package Outline & Dimensions



Symbol	Inches			Millimeters		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.031	-	0.048	0.80	-	1.22
A1	0.000	-	0.008	0.013	-	0.15
A2	0.020	0.035	0.042	0.75	0.90	1.07
b	0.011	-	0.020	0.30	-	0.51
b1	0.029	-	0.037	0.76	-	0.94
c	0.003	-	0.008	0.08	-	0.20
D	0.110	0.114	0.120	2.80	2.90	3.04
E	0.082	0.093	0.104	2.10	2.37	2.64
E1	0.047	0.051	0.055	1.20	1.30	1.40
e	0.075			1.92 BSC		
e1	0.008			0.20 BSC		
L	0.015	0.020	0.024	0.40	0.50	0.60
L1	(0.021)			(0.54)		
N	4			4		
θ	0°	-	8°	0°	-	8°
aaa	0.006			0.15		
bbb	0.008			0.20		
ccc	0.004			0.10		

Soldering Footprint



Symbol	Inches	Millimeters
C	(0.087)	(2.20)
E1	0.076	1.92
E2	0.068	1.72
G	0.031	0.80
X1	0.039	1.00
X2	0.047	1.20
Y	0.055	1.40
Z	0.141	3.60

NOTICE

Leiditech reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Leiditech does not assume any liability arising out of the application or use of any product described herein.